# High Speed, Dual MOSFET Driver

#### **Features**

- ▶ 10ns average rise and fall time with 1000pF load
- 2.0A peak output source/sink current
- ▶ 1.8 to 5.0V input CMOS compatible
- ▶ 4.5 to 13V total supply voltage
- Dual matched channels
- Reduced clock skew
- Low input capacitance
- Green packaging

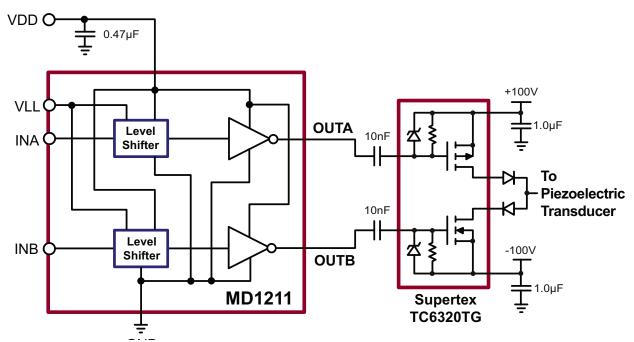
#### **Applications**

- Medical ultrasound imaging
- Piezoelectric transducer drivers
- Non-Destructive Testing (NDT)
- ► PIN diode driver
- High speed level translator
- Clock/line drivers

#### **General Description**

The Supertex MD1211 is a high speed dual MOSFET driver. It is designed to drive high voltage N and P-channel MOSFET transistors for medical ultrasound and other applications requiring a high output current for a capacitive load. The high-speed input stage of the MD1211 can operate from 1.8 to 5.0V logic interface with an optimum operating input signal range of 1.8 to 3.3V. The level translator uses a proprietary circuit, which provides DC coupling together with high-speed operation.

## **Typical Application Circuit**



## **Ordering Information**

	Package
Device	8-Lead SOIC (Narrow Body) 4.90x3.90mm body 1.75mm height (max) 1.27mm pitch
MD1211	MD1211LG-G

-G indicates package is RoHS compliant ('Green')

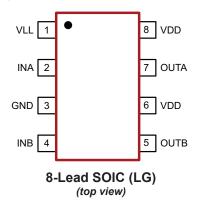


## **Absolute Maximum Ratings**

Parameter	Value
Logic supply voltage	-0.5V to +5.5V
Main supply voltage	-0.5V to +13.5V
Logic input levels	-0.5V to V <sub>LL</sub> +0.5V
Maximum junction temperature	+125°C
Storage temperature	-65°C to +150°C
Operating temperature	-20°C to +85°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

### **Pin Configuration**



### **Product Marking**



YY = Year Sealed WW = Week Sealed L = Lot Number \_ = "Green" Packaging

Package may or may not include the following marks: Si or §

8-Lead SOIC (LG)

#### **DC Electrical Characteristics**

(Over operating conditions unless otherwise specified,  $V_{DD} = 12V$ ,  $T_A = 25$ °C)

Sym	Parameter	Min	Тур	Max	Units	Conditions
V <sub>DD</sub>	Main supply voltage	4.5	-	13	V	
V <sub>LL</sub>	Logic supply voltage	1.8	-	5.0	V	
V <sub>IH</sub>	Input logic voltage high	V <sub>LL</sub> -0.3	-	V <sub>LL</sub>	V	
V <sub>IL</sub>	Input logic voltage low	0	-	8.0	V	For Logic Inputs INIA and INID
I <sub>IH</sub>	Input logic current high	-	-	10	μA	For Logic Inputs INA and INB
I	Input logic current low	-	-	10	μA	
C <sub>IN</sub>	Logic input capacitance	-	5.0	10	pF	All Inputs

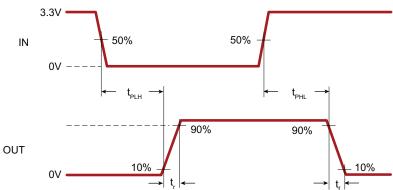
#### **Outputs**

R <sub>SINK</sub>	Output sink resistance	-	-	12	Ω	I <sub>SINK</sub> = 50mA
R <sub>SOURCE</sub>	Output source resistance	-	-	12	Ω	I <sub>SOURCE</sub> = 50mA
ISINK	Peak output sink current	-	2.0	-	Α	
SOURCE	Peak output source current	-	2.0	-	Α	

## **AC Electrical Characteristics**

Sym	Parameter	Min	Тур	Max	Units	Conditions		
t <sub>PLH</sub>	Propagation delay when output is from low to high	-	10	-	ns	C <sub>LOAD</sub> = 1000pF,		
t <sub>PHL</sub>	Propagation delay when output is from high to low		10	-	ns	(see timing diagram)		
t <sub>r</sub>	Output rise time	-	10	-	ns	Input signal rise/fall time 2ns		
t <sub>f</sub>	Output fall time	-	10	-	ns			
lt <sub>r</sub> -t <sub>f</sub> l	Rise and fall time matching	-	2.0	-	ns			
I t <sub>PLH</sub> -t <sub>PHL</sub> I	Propagation low to high and high to low matching	-	2.0	-	ns	For each channel		
$\Delta t_{\sf dm}$	Propagation delay match	-	3.0	-	ns	Device to device delay match		

# **Timing Diagram**



## **Power-Up Sequence**

Step	Connection
1	VLL with logic signal low
2	VDD
3	Logic control signals

## **Power-Down Sequence**

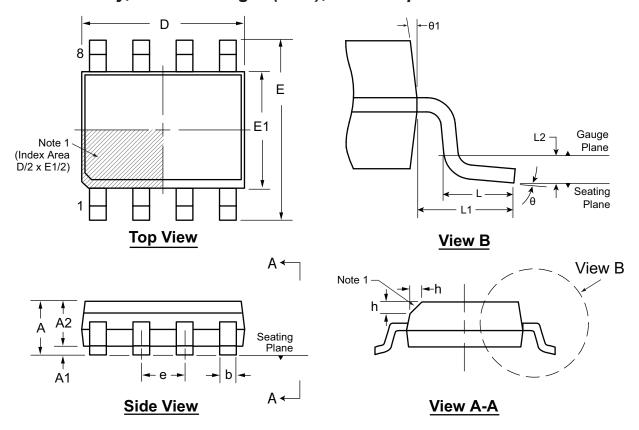
Step	Connection
1	All logic control signals go to low
2	VDD
3	VLL

# **Pin Description**

Pin#	Name	Description
1	VLL	Logic supply voltage
2	INA	Logic input
3	GND	Device ground
4	INB	Logic input
5	OUTB	Output driver
6	VDD	Main supply voltage
7	OUTA	Output driver
8	VDD	Main supply voltage

# 8-Lead SOIC (Narrow Body) Package Outline (LG)

4.90x3.90mm body, 1.75mm height (max), 1.27mm pitch



#### Note:

1. This chamfer feature is optional. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	I	A	<b>A</b> 1	A2	b	D	E	E1	е	h	L	L1	L2	θ	θ1
Dimension (mm)	MIN	1.35*	0.10	1.25	0.31	4.80*	5.80*	3.80*		0.25	0.40			<b>0</b> o	5°
	NOM	-	-	-	-	4.90	6.00	3.90	1.27 BSC	-	-	1.04 REF	0.25 BSC	-	-
()	MAX	1.75	0.25	1.65*	0.51	5.00*	6.20*	4.00*		0.50	1.27			<b>8</b> º	15°

JEDEC Registration MS-012, Variation AA, Issue E, Sept. 2005.

Drawings are not to scale.

Supertex Doc. #: DSPD-8SOLGTG, Version 1041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <a href="http://www.supertex.com/packaging.html">http://www.supertex.com/packaging.html</a>.)

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<sup>\*</sup> This dimension is not specified in the JEDEC drawing.